



**SLOVENSKI STANDARD**  
**SIST EN IEC 61189-2-809:2025**

**01-marec-2025**

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**Preskusne metode za električne materiale, tiskana vezja in druge povezovalne strukture in sestave - 2-809. del: Preskus X/Y CTE s termomehansko analizo (TMA) za tanke podložne materiale**

Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-809: X/Y Coefficient of Thermal Expansion Test (CTE) for Thick Base Materials by TMA

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen – Teil 2-809: Prüfung des X/Y-Wärmeausdehnungskoeffizienten (CTE) für dicke Grundwerkstoffe mittels TMA

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-809: Essai du coefficient de dilatation thermique (CTE) X/Y pour matériaux de base épais à l'aide d'un analyseur thermomécanique (TMA)

**Ta slovenski standard je istoveten z: EN IEC 61189-2-809:2025**

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**ICS:**

31.180 Tiskana vezja (TIV) in tiskane Printed circuits and boards plošče

**SIST EN IEC 61189-2-809:2025**

**en**



EUROPEAN STANDARD

EN IEC 61189-2-809

NORME EUROPÉENNE

EUROPÄISCHE NORM

January 2025

ICS 31.180

English Version

Test methods for electrical materials, circuit boards and other  
interconnection structures and assemblies - Part 2-809: X/Y  
coefficient of thermal expansion (CTE) test for thick base  
materials by TMA  
(IEC 61189-2-809:2024)

Méthodes d'essai pour les matériaux électriques, les  
circuits imprimés et autres structures d'interconnexion et  
ensembles - Partie 2-809: Essai du coefficient de dilatation  
thermique (CTE) X/Y pour matériaux de base épais à l'aide  
d'un analyseur thermomécanique (TMA)  
(IEC 61189-2-809:2024)

Prüfverfahren für Elektromaterialien, Leiterplatten und  
andere Verbindungsstrukturen und Baugruppen - Teil 2-  
809: Prüfung des X/Y-Wärmeausdehnungskoeffizienten  
(CTE) für dicke Grundwerkstoffe mittels TMA  
(IEC 61189-2-809:2024)

This European Standard was approved by CENELEC on 2025-01-13. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

## EN IEC 61189-2-809:2025 (E)

### European foreword

The text of document 91/1983/FDIS, future edition 1 of IEC 61189-2-809, prepared by TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-2-809:2025.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2026-01-31 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2028-01-31 document have to be withdrawn

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

Any feedback and questions on this document should be directed to the users' national committee. A complete listing of these bodies can be found on the CENELEC website.

### Endorsement notice

The text of the International Standard IEC 61189-2-809:2024 was approved by CENELEC as a European Standard without any modification.

[SIST EN IEC 61189-2-809:2025](https://standards.iteh.ai/catalog/standards/sist/900350bb-71c7-4d7c-9d57-d69253f85b8f/sist-en-iec-61189-2-809-2025)

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cencenelec.eu](http://www.cencenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-1	-	Printed boards design, manufacture and assembly - Vocabulary - Part 1: Common usage in printed board and electronic assembly technologies	-	-
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-

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